MICROCHIP

Semiconductor Device Type:	J7X	DDPAK 5L Matte Tin			
Basic Substance	**CAS Number**	**"Contained In" Sub-Component**	**% Total Weight**	**mg/part**	**ppm**
Silicon	7440-21-3	Die	0.41	0.06	4106
Copper	7440-50-8	Leadframe	53.35	8.24	533503
Iron	7439-89-6	Leadframe	0.03	0.00	267
Phosphorus	7723-14-0	Leadframe	0.01	0.00	133
Silver	7440-22-4	Leadframe	0.01	0.00	80
Silver	7440-22-4	Die Attach Material	0.09	0.01	914
Epoxy Resin	9003-36-5	Die Attach Material	0.01	0.00	54
Diluent A	Trade Secret	Die Attach Material	0.00	0.00	1
P-tert-Butylphenyl Glycidyl Ether	3101-60-8	Die Attach Material	0.00	0.00	1
Hardener A	Trade Secret	Die Attach Material	0.00	0.00	1
Hardener B	Trade Secret	Die Attach Material	0.00	0.00	1
Solvent	Trade Secret	Die Attach Material	0.00	0.00	5
Organic Peroxide	Trade Secret	Die Attach Material	0.00	0.00	5
Gold	7440-57-5	Gold Wire Bump	0.22	0.03	2208
Other	Trade Secret	Gold Wire Bump	0.00	0.00	0
Copper	7440-50-8	Bonding Wire	3.24	0.50	32394
Other	Trade Secret	Bonding Wire	0.00	0.00	3
Epoxy Resin A	Trade secret	Mold Compound	2.13	0.33	21290
Epoxy Resin B	29690-82-2	Mold Compound	1.28	0.20	12774
Phenol Resin	Trade secret	Mold Compound	1.28	0.20	12774
Vitreous Silica	60676-86-0	Mold Compound	36.19	5.59	361927
Silica	7631-86-9	Mold Compound	1.28	0.20	12774
Carbon Black	1333-86-4	Mold Compound	0.43	0.07	4258
Tin	7440-31-5	Lead Finish Plating	0.05	0.01	526
Other	Trade Secret	Lead Finish Plating	0.00	0.00	0
		TOTALS:	**100.00**	**15.44**	**1,000,000**

15.44 mg Total Mass

Package Homogeneous Materials

0.06	**(mg) Total**	**Die**	**% of Total Weight**	**0.41**
	Silicon	7440-21-3	100.00	
		Total	**100.00**	
8.25	**(mg) Total**	**Leadframe**	**% of Total Weight**	**53.40**
	Copper	7440-50-8	99.91	
	Iron	7439-89-6	0.05	
	Phosphorus	7723-14-0	0.03	
	Silver	7440-22-4	0.02	
		Total	**100.00**	
0.02	**(mg) Total**	**Die Attach Material**	**% of Total Weight**	**0.10**
	Silver	7440-22-4	93.03	
	Epoxy Resin	9003-36-5	5.54	
	Diluent A	Trade Secret	0.08	
	P-tert-Butylphenyl Glycidyl Ether	3101-60-8	0.08	
	Hardener A	Trade Secret	0.08	
	Hardener B	Trade Secret	0.08	
	Solvent	Trade Secret	0.55	
	Organic Peroxide	Trade Secret	0.55	
		Total	**100.00**	
0.03	**(mg) Total**	**Gold Wire Bump**	**% of Total Weight**	**0.22**
	Gold	7440-57-5	99.99	
	Other	Trade Secret	0.01	
		Total	**100.00**	
0.50	**(mg) Total**	**Bonding Wire**	**% of Total Weight**	**3.24**
	Copper	7440-50-8	99.99	
	Other	Trade Secret	0.01	
		Total	**100.00**	
6.58	**(mg) Total**	**Mold Compound**	**% of Total Weight**	**42.58**
	Epoxy Resin A	Trade secret	5.00	
	Epoxy Resin B	29690-82-2	3.00	
	Phenol Resin	Trade secret	3.00	
	Vitreous Silica	60676-86-0	85.00	
	Silica	7631-86-9	3.00	
	Carbon Black	1333-86-4	1.00	
		Total	**100.00**	
0.01	**(mg) Total**	**Lead Finish Plating**	**% of Total Weight**	**0.05**
	Tin	7440-31-5	99.99	
	Other	Trade Secret	0.01	
15.44		**Total**	**100.00**	100.00

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